

• General Description

The AGMH022N10H combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

This device is ideal for load switch and battery protection applications.

Features

- Advance high cell density Trench technology
- Low R_{DS(ON)} to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance
- 100% Avalanche test
- 100% DVDS tested

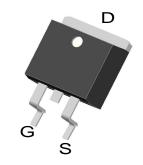
Application

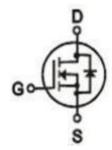
- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

Product Summary

BVDSS	RDSON	ID
100V	2.2mΩ	220A

TO-263 Pin Configuration





Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AGMH022N10H	AGMH022N10H	TO-263	330mm	25mm	800

Table 1. Absolute Maximum Ratings (TC=25℃)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	100	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
ID	Drain Current-Continuous(Tc=25℃) (Note 1)	220	А
	Drain Current-Continuous(Tc=100℃)	132	Α
IDM (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 2)	880	А
PD	Maximum Power Dissipation(Tc=25℃)	300	w
	Maximum Power Dissipation(Tc=100℃)	150	w
EAS	Avalanche energy (Note 3)	1800	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 175	$^{\circ}$

Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
RθJC	Thermal Resistance Junction-Case ¹		0.5	°C/W



Table 3. Electrical Characteristics (TC=25°Cunless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
On/Off States						
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=250µA	100			V
IDSS	Zero Gate Voltage Drain Current	VDS=100V,VGS=0V			1	μΑ
IGSS	Gate-Body Leakage Current	VGS=±20V,VDS=0V			±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS,ID=250μA	2.5	3.5	4.5	V
gFS	Forward Transconductance	VDS=5V,ID=10A		36		S
RDS(on)	Drain-Source On-State Resistance	VGS=10V, ID=50A		2.2	2.7	mΩ
Dynamic (Characteristics					
Ciss	Input Capacitance	VDS=50V,VGS=0V,		11500		pF
Coss	Output Capacitance	F=1MHZ		1480		pF
Crss	Reverse Transfer Capacitance			75		pF
Switching	Times		1			
td(on)	Turn-on Delay Time			25		nS
tr	Turn-on Rise Time	VGS=10V,VDS=50V,		75		nS
td(off)	Turn-Off Delay Time	ID=100A,RGEN=1.6Ω		89		nS
tf	Turn-Off Fall Time			29		nS
Qg	Total Gate Charge			158		nC
Qgs	Gate-Source Charge	VGS=10V, VDS=50V, ID=100A		52		nC
Qgd	Gate-Drain Charge	- IB-100A		29		nC
Source-Drain Diode Characteristics						
ISD	Source-Drain Current(Body Diode)				220	Α
VSD	Forward on Voltage	VGS=0V,IS=20A			1.2	V
trr	Reverse Recovery Time	IF=20A , dl/dt=100A/μs ,		75		ns
Qrr	Reverse Recovery Charge	TJ=25℃		185	-	nc

Notes 1. The maximum current rating is package limited.

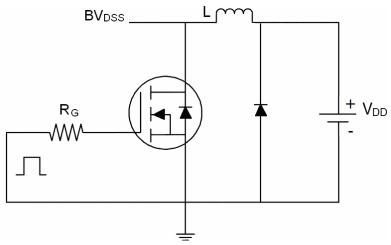
Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

Notes 3.EAS condition: TJ=25℃

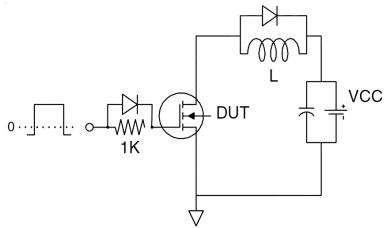


Test Circuit

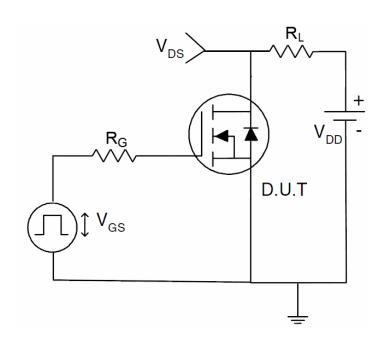
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit







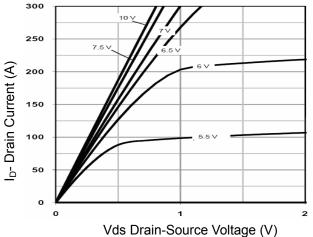


Figure 1 Output Characteristics

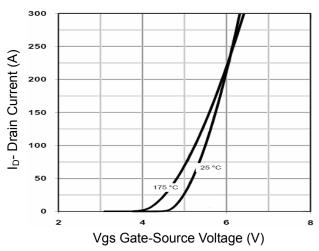


Figure 2 Transfer Characteristics

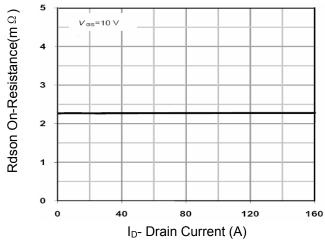


Figure 3 Rdson- Drain Current

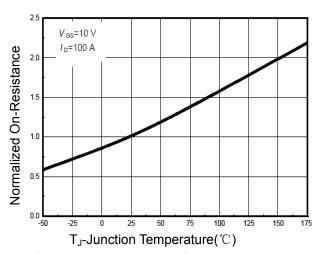


Figure 4 Rdson-Junction Temperature

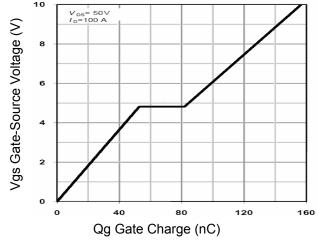


Figure 5 Gate Charge

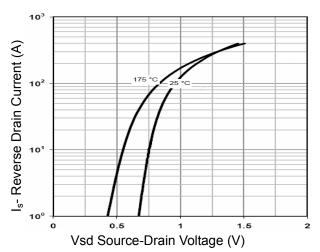
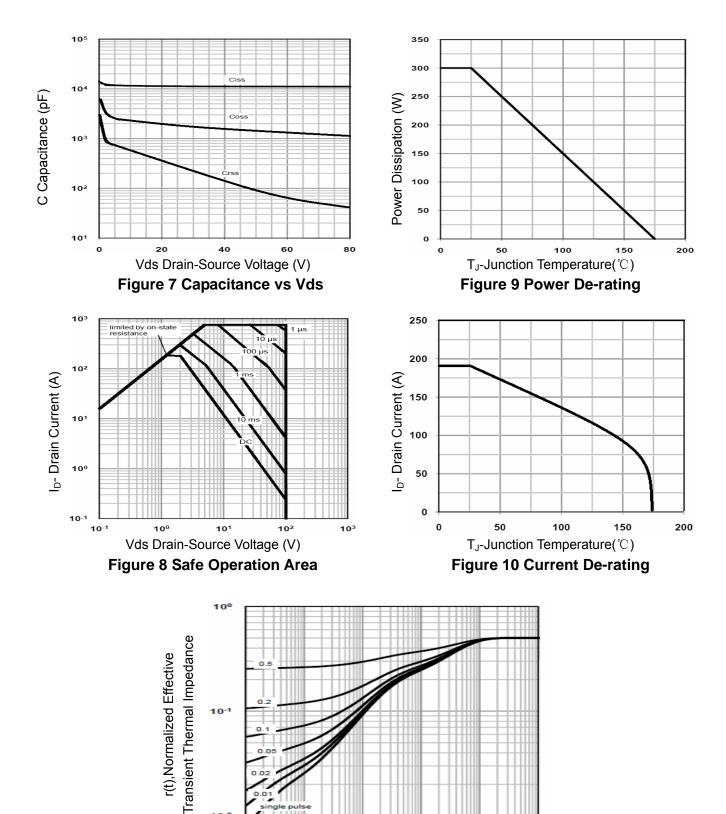


Figure 6 Source- Drain Diode Forward





Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance

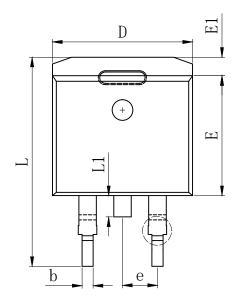
10°

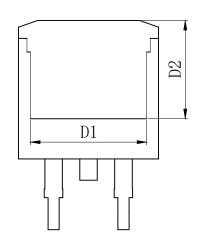
10-3

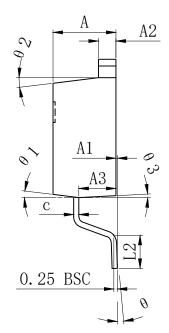
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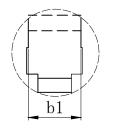


TO-263 PACKAGE INFORMATION









	MILLIMETER				
SYMBOL	MIN Typ.		MAX		
A	4. 370 4. 570 4		4.770		
A1	0.000		0.250		
A2	1. 220	1. 220 1. 270			
А3	2. 490	2. 690	2.890		
b	0.700	0.960			
b1	1. 170	1. 270	1.470		
С	0.300	0.380	0.530		
D	9. 860 10. 160		10. 360		
D1	8. 400 REF				
D2		7.073 REF			
Е	8. 500	8. 700	8.900		
E1	1.070 1.270		1.470		
е	2.540 TYP				
L	14. 700	15. 100	15. 500		
L1	1. 400	1.550	1.700		
L2	2.000	2.300	2.600		
θ	0° 9°		9°		
θ 1	7° TYP				
θ2	7° TYP				
θ 3	3° TYP				



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